

单通道ESD保护二极管

UM5035 SOD323

描述

UM5035 ESD保护二极管设计用于取代手机、笔记本电脑和PDA等便携式应用中的MLV。与MLV相比，该器件内置可传导高瞬态电流的大截面积结，具有板级保护的完美电气特性，例如快速响应时间、较低的工作电压、较低的钳位电压和无器件劣化。

UM5035 ESD保护二极管可保护敏感的半导体元件免受静电放电 (ESD) 和其他瞬态电压事件的损坏或破坏。UM5035采用SOD323封装，工作电压为5 V。

在阵列不实用的应用中，设计人员能够灵活地使用该器件保护单向线路。此外，在电路板空间有限的应用中，该器件可采用分散布置的布局方案。该器件可满足IEC 61000-4-2标准的第4级静电抗扰度要求： $\pm 15\text{kV}$ 空气间隙放电和 $\pm 8\text{kV}$ 接触放电。

应用

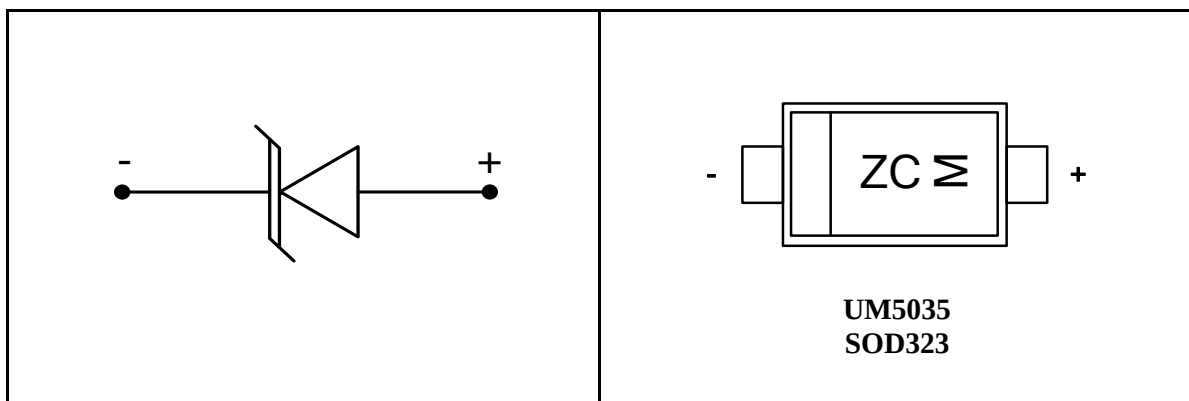
- 手机听筒及配件
- 基于微处理器的设备
- PDA
- 笔记本电脑、台式机和服务
- 便携式设备
- 无线电话
- 数码相机
- 外围设备
- MP3 播放器

特性

- 数据线和电源线瞬态保护，符合IEC 61000-4-2标准： $\pm 15\text{kV}$ （空气间隙放电）， $\pm 8\text{kV}$ （接触放电）
- 用于便携式电子设备的小型封装
- ESD保护应用中MLV的合适替代品
- 保护一路I/O或电源线
- 低钳位电压
- 反向工作电压：5V
- 低漏电流
- 固态硅雪崩技术

引脚配置

顶部视图



Ordering Information

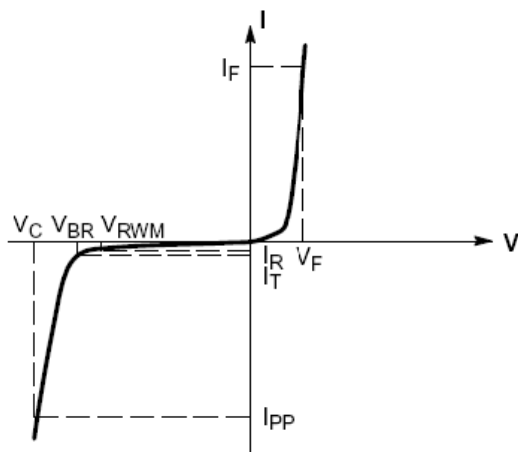
Part Number	Working Voltage	Packaging Type	Channel	Marking Code	Shipping Qty
UM5035	5.0V	SOD323	1	ZC	3000pcs/7 Inch Tape & Reel

Absolute Maximum Ratings

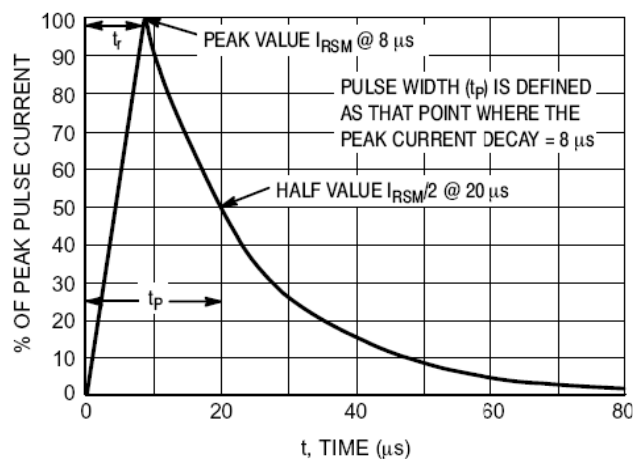
Rating	Symbol	Value	Unit
Peak Pulse Power ($t_p=8/20\mu s$)	P_{PK}	140	Watts
Maximum Peak Pulse Current ($t_p=8/20\mu s$)	I_{PP}	11	Amps
Lead Soldering Temperature	T_L	260 (10 sec.)	$^{\circ}C$
Operating Temperature	T_J	-55 to +125	$^{\circ}C$
Storage Temperature	T_{STG}	-55 to +150	$^{\circ}C$

Symbol Definition

Parameter	Symbol
Maximum Reverse Peak Pulse Current	I_{PP}
Clamping Voltage @ I_{PP}	V_C
Working Peak Reverse Voltage	V_{RWM}
Maximum Reverse Leakage Current @ V_{RWM}	I_R
Breakdown Voltage @ I_T	V_{BR}
Test Current	I_T
Forward Current	I_F
Forward Voltage @ I_F	V_F
Peak Power Dissipation	P_{PK}
Max. Capacitance @ $V_R=0V$, $f=1MHz$	C



Uni-Directional TVS



Electrical Characteristics

(T=25 °C, Device for 5.0V Reverse Stand-Off Voltage)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Reverse Stand-Off Voltage	V_{RWM}				5	V
Reverse Breakdown Voltage	V_{BR}	$I_T=1mA$	6	6.8	7.8	V
Reverse Leakage Current	I_R	$V_{RWM}=5V, T=25\text{ °C}$			0.1	μA
Clamping Voltage	V_C	$I_{PP}=5A, t_p=8/20\mu s$			9.1	V
		$I_{PP}=11A, t_p=8/20\mu s$			13	
Forward Voltage	V_F	$I_F=10mA$		0.8		V
Junction Capacitance	C_J	$V_R=0V, f=1MHz$		40	55	pF
Junction Capacitance	C_J	$V_R=2.5V, f=1MHz$		30	40	pF

Applications Information

Device Connection Options

UM5035 ESD protection diode is designed to protect one data, I/O, or power supply line. The device is unidirectional and may be used on lines where the signal polarity is above ground. The cathode band should be placed towards the line that is to be protected.

Circuit Board Layout Recommendations for Suppression of ESD

Good circuit board layout is critical for the suppression of ESD induced transients. The following guidelines are recommended:

1. Place the TVS near the input terminals or connectors to restrict transient coupling.
2. Minimize the path length between the TVS and the protected line.
3. Minimize all conductive loops including power and ground loops.
4. The ESD transient return path to ground should be kept as short as possible.
5. Never run critical signals near board edges.
6. Use ground planes whenever possible. For multilayer printed-circuit boards, use ground vias.
7. Keep parallel signal paths to a minimum.
8. Avoid running protection conductors in parallel with unprotected conductor.
9. Minimize all printed-circuit board conductive loops including power and ground loops.
10. Avoid using shared transient return paths to a common ground point.

Matte Tin Lead Finish

Matte tin has become the industry standard lead-free replacement for SnPb lead finishes. A matte tin finish is composed of 100% tin solder with large grains. Since the solder volume on the leads is small compared to the solder paste volume that is placed on the land pattern of the PCB, the reflow profile will be determined by the requirements of the solder paste. Therefore, these devices are compatible with both lead-free and SnPb assembly techniques. In addition, unlike other lead-free compositions, matte tin does not have any added alloys that can cause degradation of the solder joint.

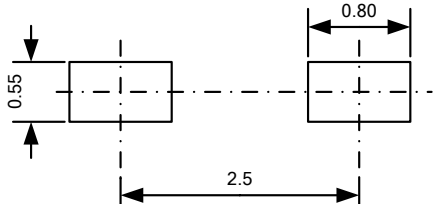
Package Information

UM5035 SOD323

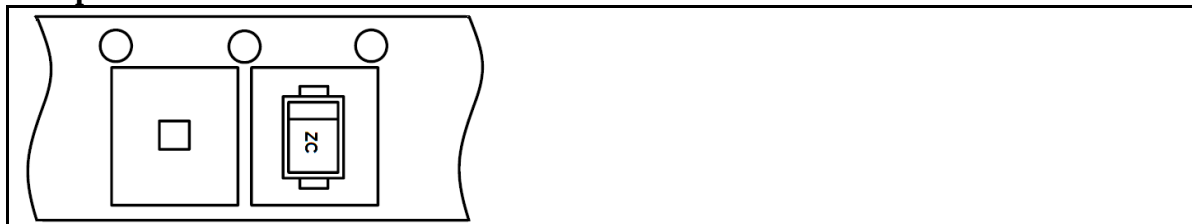
Outline Drawing

DIMENSIONS						
Symbol	MILLIMETERS			INCHES		
	Min	Typ	Max	Min	Typ	Max
A1	1.00	1.05	1.10	0.04	0.042	0.044
A2	-	0.05	0.10	-	0.002	0.004
b	0.25	0.30	0.35	0.01	0.012	0.014
c	0.10	0.11	0.15	0.004	0.044	0.006
D	1.20	1.30	1.40	0.048	0.052	0.056
E	1.60	1.70	1.80	0.064	0.068	0.072
E1	2.30	2.50	2.70	0.092	0.10	0.108
L	0.20	0.30	0.40	0.008	0.012	0.016
θ	8° REF			8° REF		

Land Pattern

	NOTES: 1. Compound dimension: 1.70×1.30; 2. Unit: mm; 3. General tolerance $\pm 0.05\text{mm}$ unless otherwise specified; 4. The layout is just for reference.
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Tape and Reel Orientation



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